Plastronics

H057 contact

DC Measurement Results

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8/7/2008

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Objective

The objective of these measurements is to determine the DC current carrying ability, resistance, and temperature rise during operation.

Methodology

A four terminal (Kelvin) measurement setup is used that includes a computer controlled voltage source as well as a current source capable of delivering 10 A. The voltage developed across the contact is recorded in a Kelvin (four terminal) measurement at separate terminals.

Test procedures

During testing drive current is increased in steps of 50 mA to the maximum value. Because of the low thermal mass a fast response of the contact itself occurs. The dwell time for each current step is thus set to 10 seconds.

Setup

For current handling tests, all contacts are isolated except for one.

The H057 contact test components are placed between two metal plates. Au over Ni plating was applied to the surfaces of the brass plates. A four terminal (Kelvin) measurement setup is used that included a computer controlled current source capable of delivering 10 A. The voltage developed across the contact is recorded at separate terminals with an HP3456A digital voltmeter.

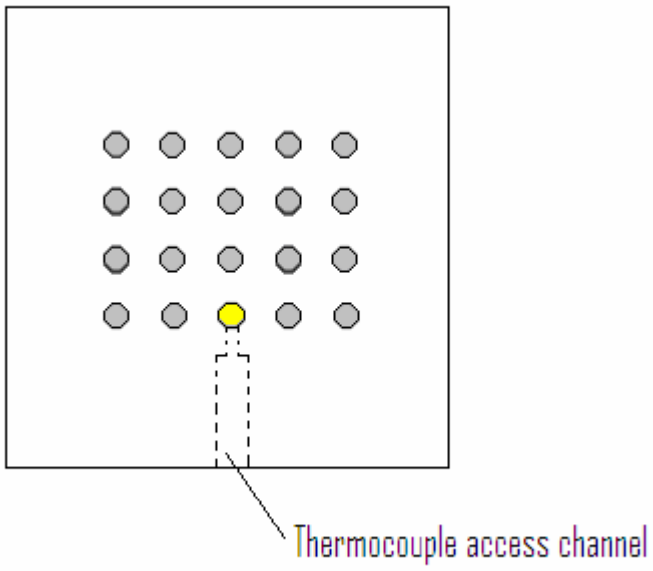
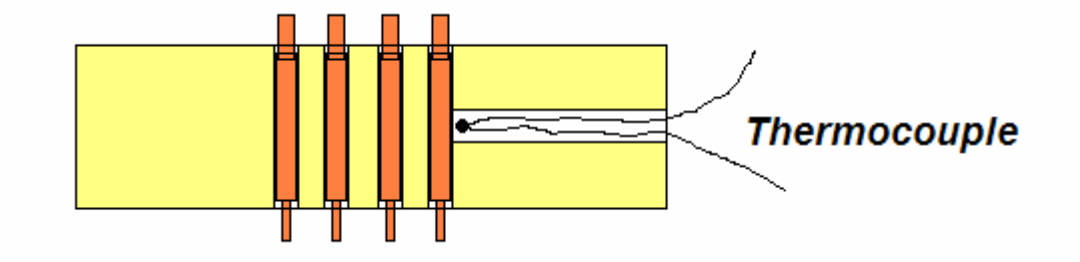


Fig. 1 H057 contact test arrangement

Once the data are available, they are processed to reveal the resistance and power dissipation as a function of drive current.

A second digital meter records the temperature of a small thermocouple (0.010”) located near the driven pin. The thermocouple’s access location is about in the center of the pin.

The H057 contact is modified to allow thermocouple access and held in a fixture similar to the one shown in Fig. 2:



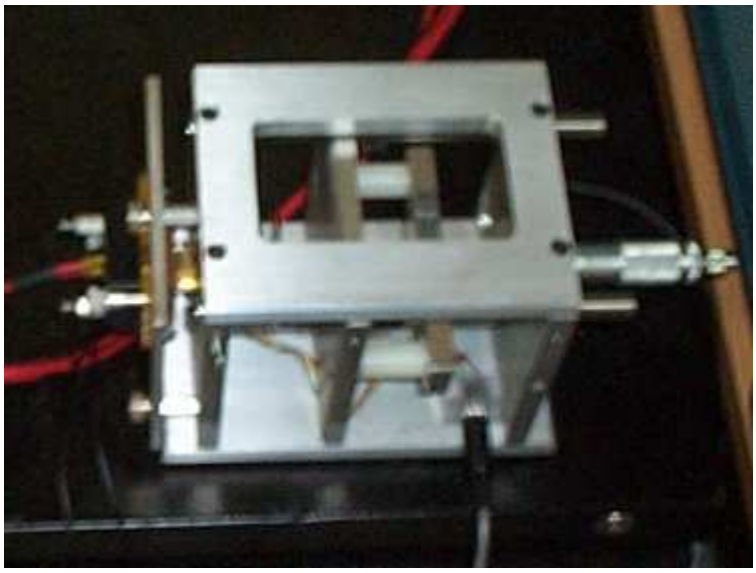


Fig. 2 H057 contact mounting and fixturing example

Measurements

Current carrying capability (socket)

The measured current – voltage relationship for the H057 contact is shown below:

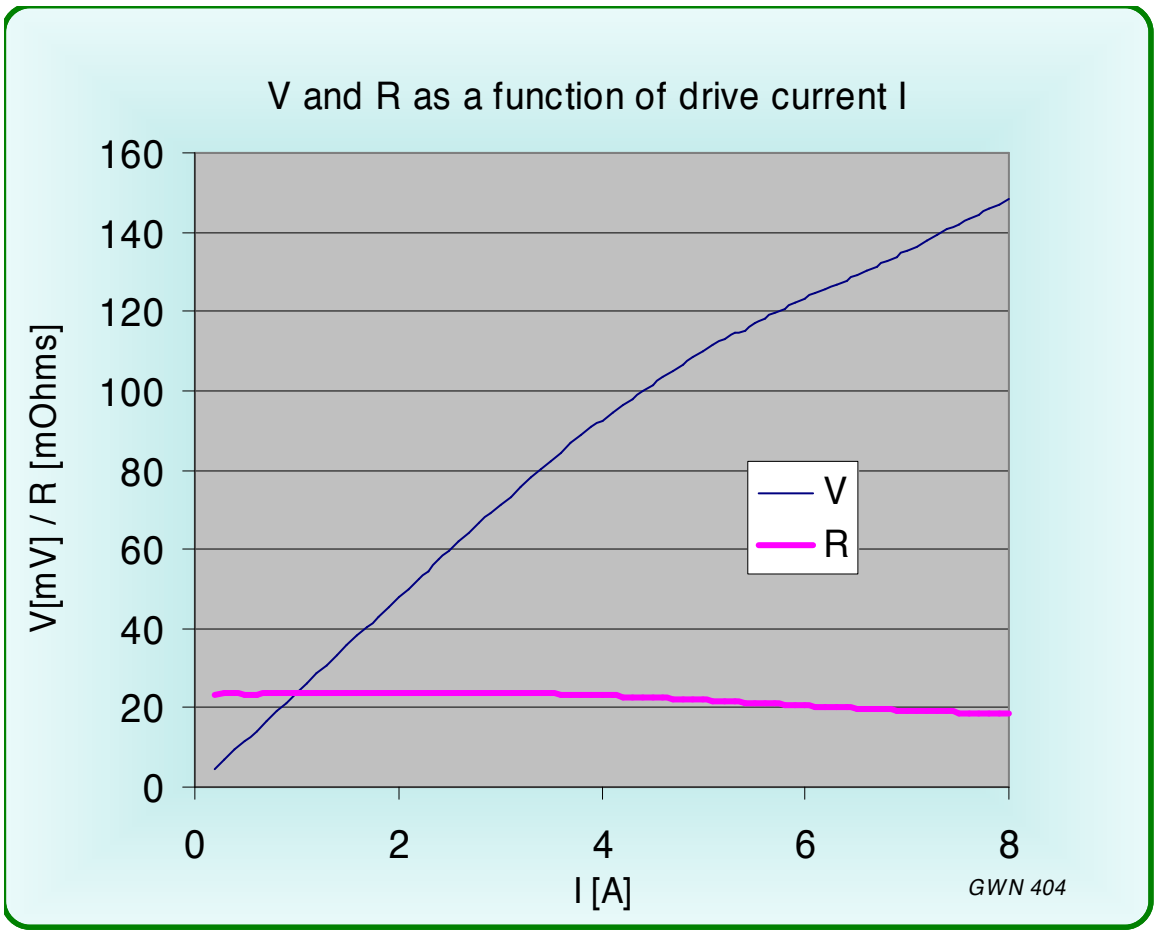


Fig. 3 Voltage and resistance as a function of drive current

No thermal runaway occurs up to the maximum tested current of 8A.

The accompanying power dissipation in the connection is computed from applied current and observed voltage:

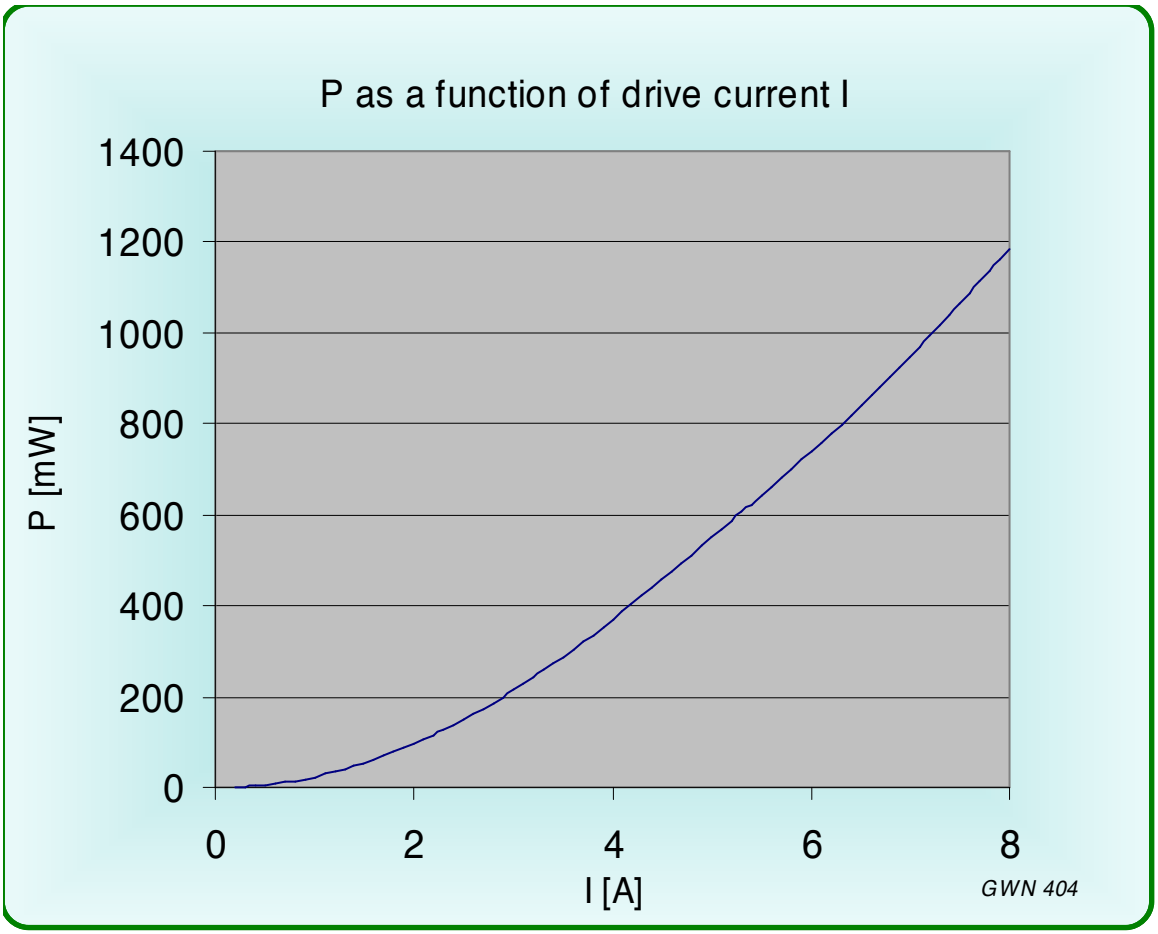


Fig. 4 Power dissipation as a function of drive current

Another important parameter is the temperature rise as a function of drive level. As stated above the temperature rise is measured via thermocouple in proximity with the pin. This implies that temperature readings at the thermocouple will be lower than those at and inside the pin itself.

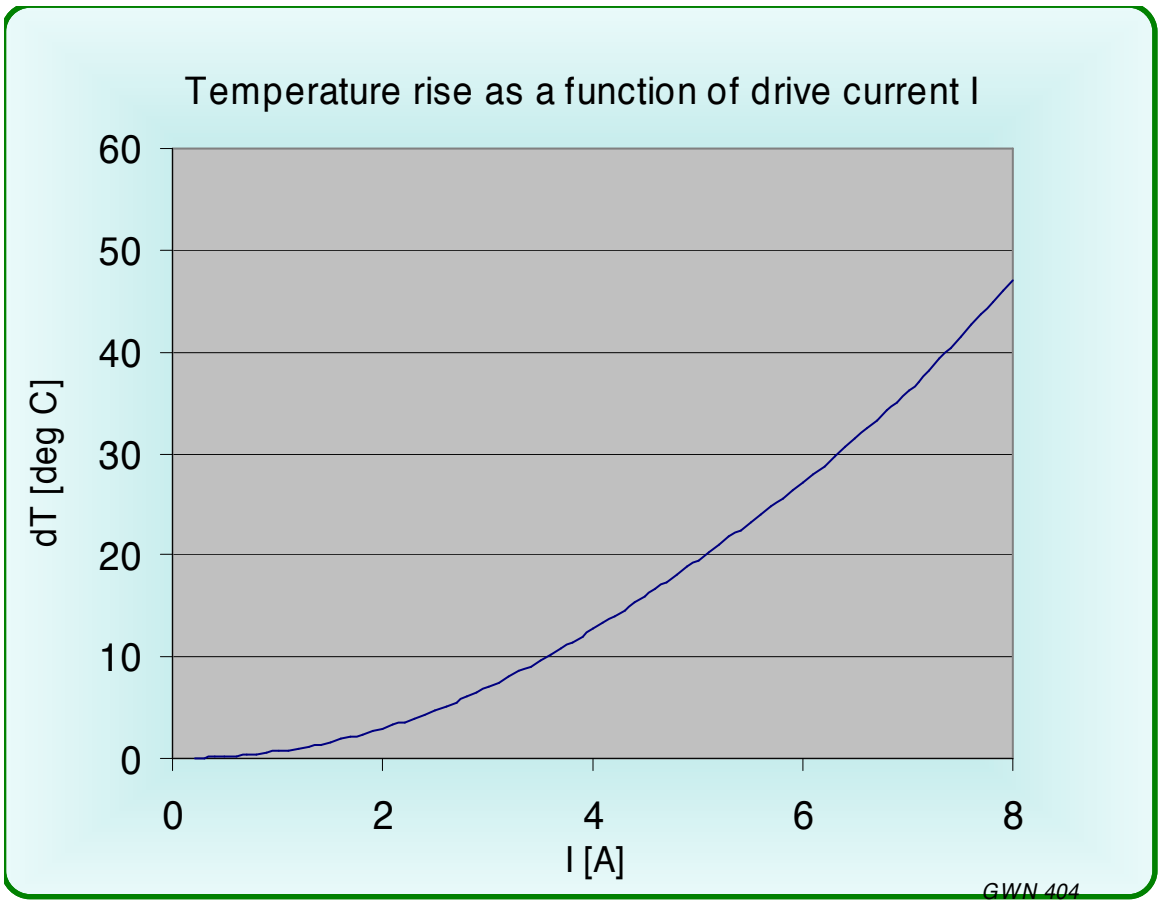
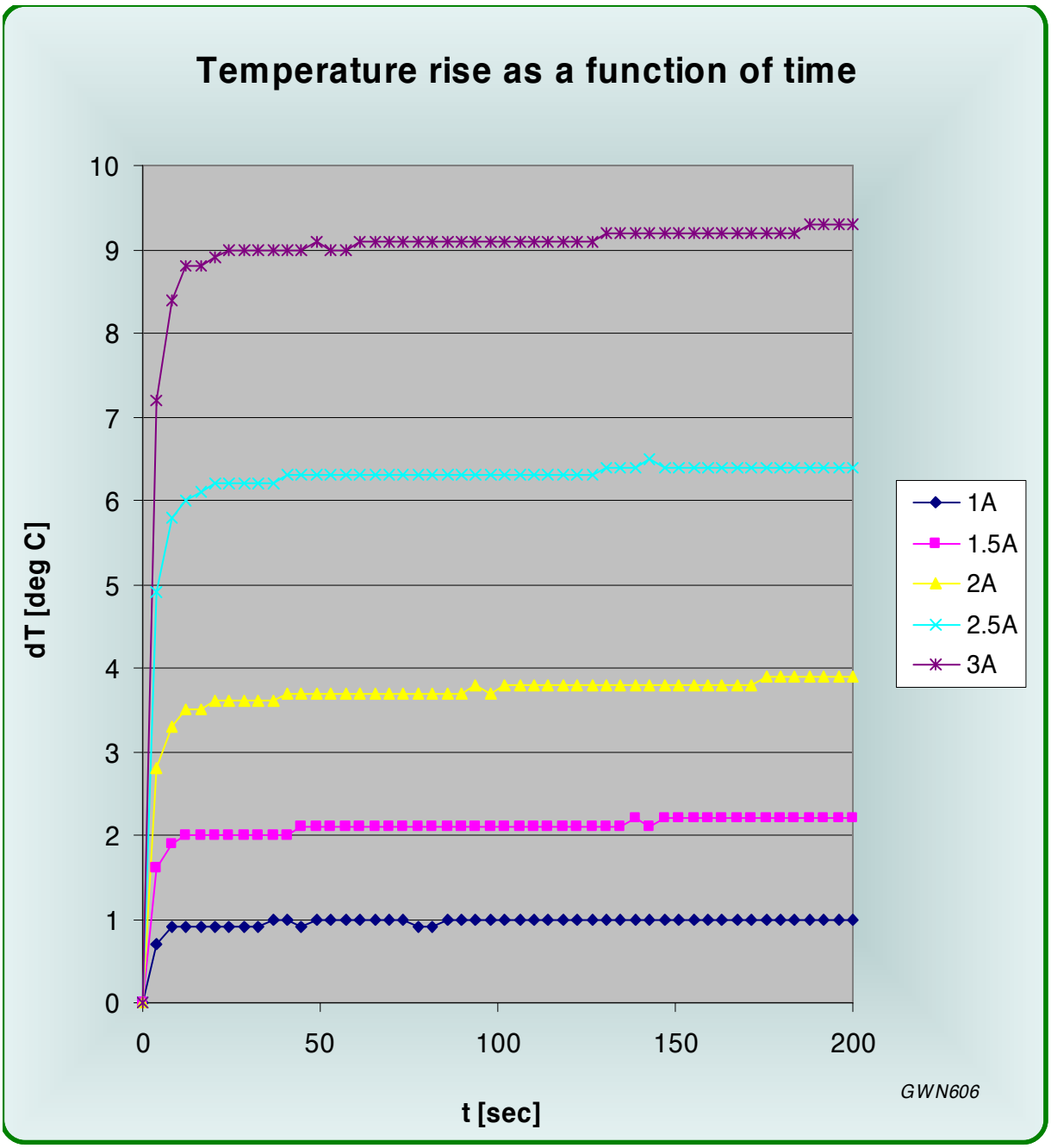


Fig. 5 Temperature rise as a function of drive current

It should be kept in mind that the metal contacts at either end afford excellent heat removal from the contact area. In an environment with lower thermal conductivity the temperature rise during testing and the subsequent resistance increase as well as the current handling may therefore be different than indicated here. This holds especially true for thick circuit boards where ground and power planes are far from the contact point.

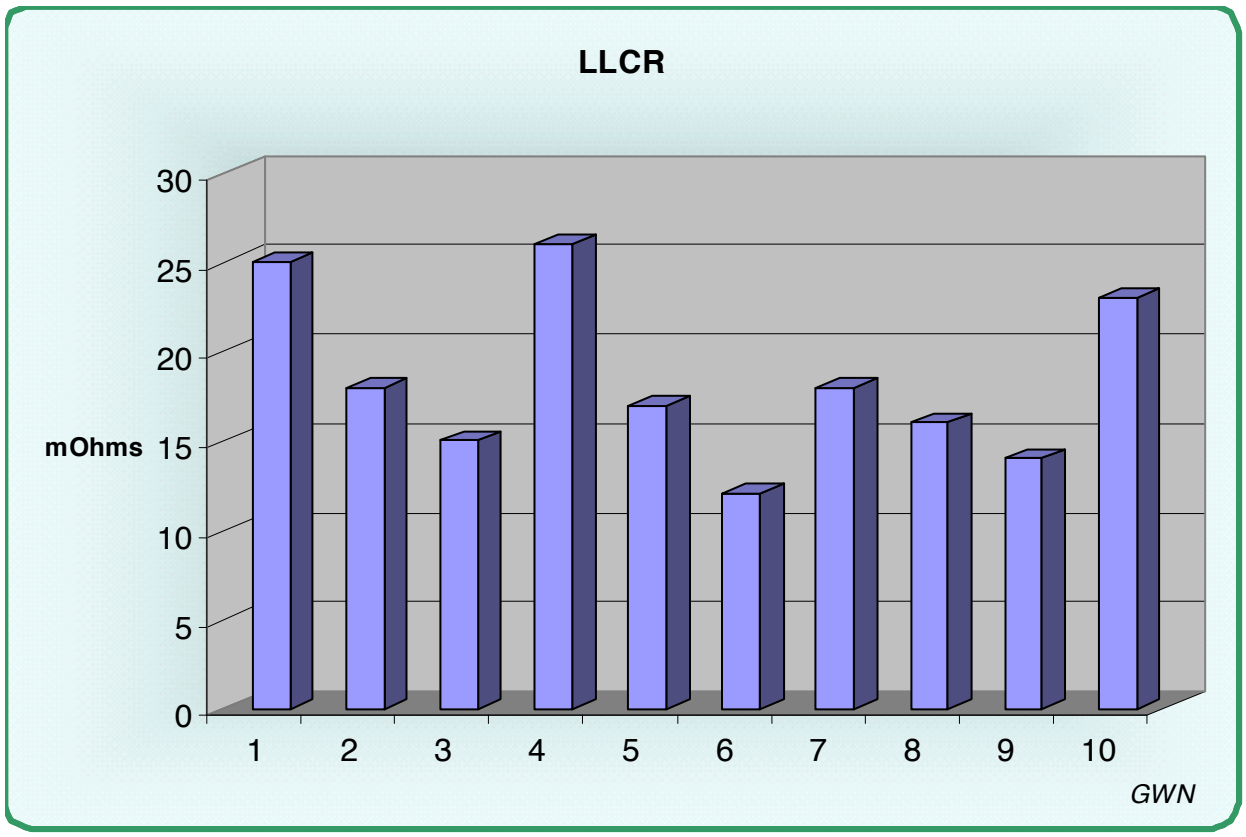
Another set of data was acquired with the drive current held constant and while recording temperature as a function of time. The result is shown in Fig. 6 below:



Because of the low thermal mass of the contact under load the initial temperature rise is very rapid. The slow increase of temperature with time up to about 200 seconds is likely due to gradual warm-up of the surroundings and the metal structures that feed current to the contact.

Low level contact resistance

For a total of 10 different contacts the LLCR was determined as follows:



LLCR for 10 different contacts

Statistical evaluation yields the following:

AVERAGE Cres	18.4	mOhms
Max	26	mOhms
Min	12	mOhms
STDEV	4.7	mOhms